




### General

- Inrush withstand capability
- Wire-In-Air technology
- Wide range of current rating available
- 6.1mm× 2.5mm square shape surface mount
- Higher temperature profiles
- -55°C~125°C operating temperature
- Excellent environmental integrity
- RoHS compliant
- Halogen-free

### Agency / Certificate Information

Agency	File Number	Ampere Range
	E319512	0.5A~5A
	J50260452	0.5A~5A
	SU05049-15003A	0.5A
	SU05049-15001	1A~2.5A
	SU05049-15002	3A~5A

### Application

- Battery pack
- Power supply
- PC & PC peripherals
- PC server
- Wireless basestation
- Industrial equipment
- Telecom system
- LCD monitor and modules
- Medical equipment

### Electrical Specifications

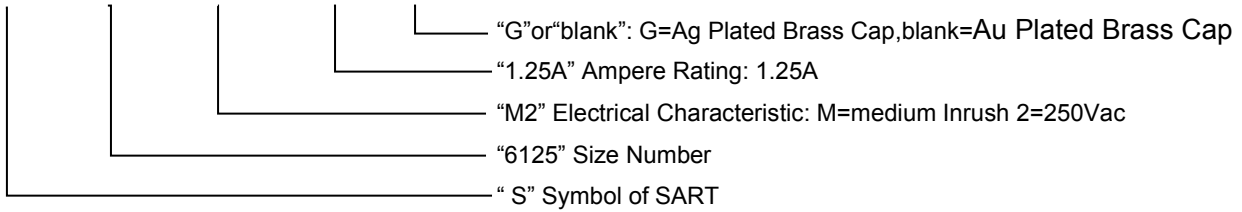
Part Number	Current Rating (A)	Voltage Rating (V)	Interrupting Rating (V)	Typical Cold DCR* (mΩ)	Typical I <sup>2</sup> T** (A <sup>2</sup> sec)
S6125-M2-0.5A G	0.5	250	UL/TUV/KC 35A 250V AC 50A 125V DC	260.0	0.285
S6125-M2-1.0A G	1	250	UL/TUV/KC 50A 250V AC 50A 125V DC	119.0	1.54
S6125-M2-1.25A G	1.25	250		84.0	2.42
S6125-M2-1.5A G	1.5	250		76.0	3.03
S6125-M2-1.6A G	1.6	250		70.0	3.99
S6125-M2-2.0A G	2	250		55.0	4.86
S6125-M2-2.5A G	2.5	250		38.0	7.58
S6125-M2-3.0A G	3	250		27.0	10.62
S6125-M2-3.15A G	3.15	250		24.0	12.40
S6125-M2-3.5A G	3.5	250		22.0	16.17
S6125-M2-4.0A G	4	250		20.0	20.00
S6125-M2-5.0A G	5	250		13.0	27.50

\* Measured at ≤10% rated current and 25°C

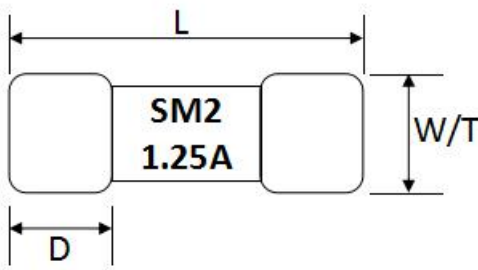
\*\* Melting I<sup>2</sup>T at 10 times of rated current

### Part Number Information

S 6125–M2–1.25A G

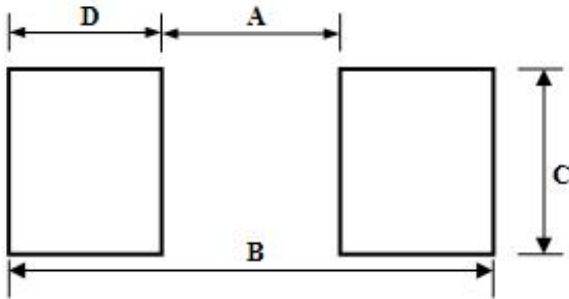


### Dimensions



Type	L (mm)	W/ T (mm)	D (mm)
S6125	6.10±0.20	2.50±0.10	1.40±0.10

### Recommended Land Patterns



### Materials

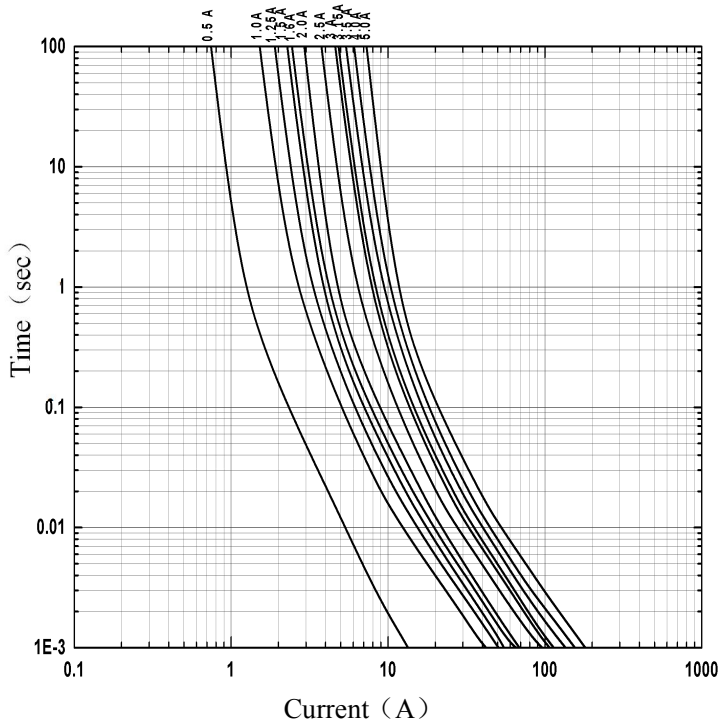
Components	Material
Body	Ceramic
Terminations	Au Plated Brass Cap or Ag Plated Brass Cap
Element	Nickel alloy or Copper Alloy

Type	A(mm)	B(mm)	C(mm)	D(mm)
S6125	3.00±0.30	8.00±0.30	3.00±0.30	2.50±0.30

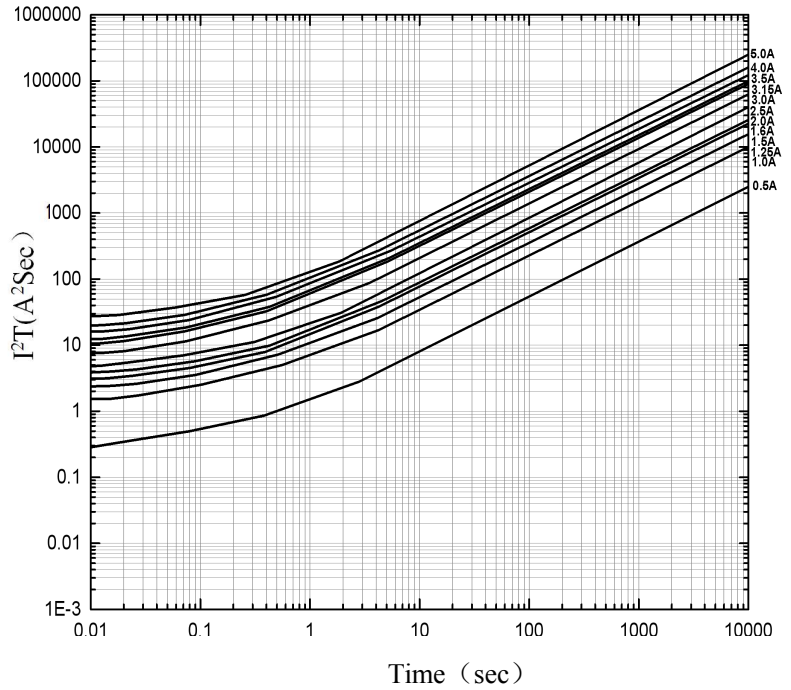
### Dimensions of Standard Test Board

Type	Ampere Rating	Board Thickness (mm)	Copper Layer Thickness (mm)	Copper Trace Width (mm)
S6125	0.5A~5A	1.6	0.035	5

### Time Current Curve



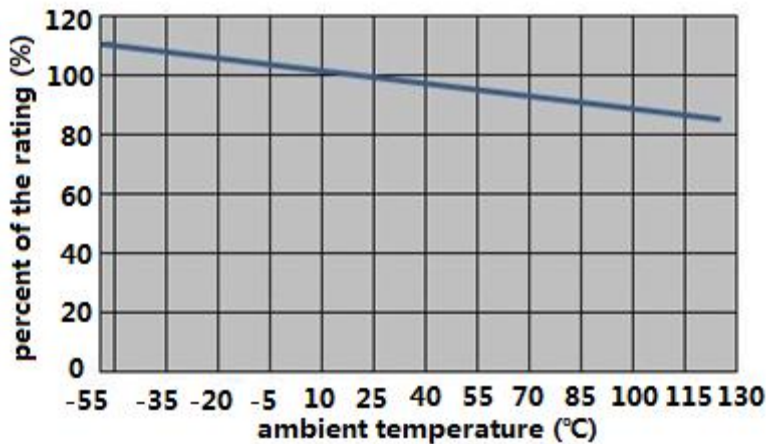
### I<sup>2</sup>T VS Time Curve



### Electrical Characteristics

Type	Ampere Rating	% of Current Rating	Opening Time
S6125	0.5A~5A	100	4hours Min.
	0.5A~5A	200	120sec Max.

### Temperature Derating Curve



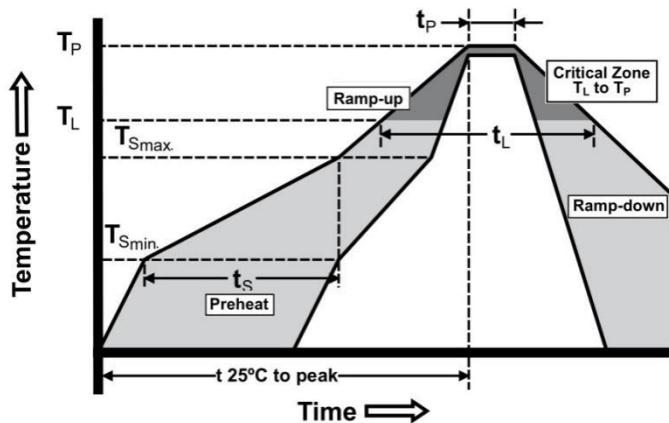
## Product Characteristics

Item	Test condition/ Methods	Performance	Standard
Time/Current	100% of current rating	No Fusing, 4hours Min.	UL248-14
	200% of current rating	< 120sec	SART SPEC
	1000% of current rating	> 10msec	IEC60127-4
Voltage Drop	100% of current rating	< 300mV	IEC-60127-4
Endurance Test	Repeating 100 cycles of 100% of current rating for 1hour "ON", for 15min "OFF", then following by 1hour of 125% of current rating and testing Temperature rise	$ \Delta R  < 10\%$ $\Delta T < 75^\circ\text{C}$	IEC-60127-4
Interrupting Ability	0.5A: 35A 250V AC 50A 125V DC 1A~5A: 50A 250VAC 50A 125VDC	without permanent arcing, ignition and bursting of fuse link	UL248-14 IEC60127-4
Solder ability	$240^\circ\text{C} \pm 5^\circ\text{C}$ , 3sec $\pm$ 0.5sec	95% coverage Min.	IEC60127-4 IEC60068-2-20; MIL-STD-202
Resistance to Soldering	$260^\circ\text{C} \pm 5^\circ\text{C}$ , 10sec $\pm$ 0.5sec	$ \Delta R  < 10\%$	MIL-STD-202 Method 210
High Temperature Operating Life	$T=70^\circ\text{C} \pm 2^\circ\text{C}$ , 60% of current rating, 96 hours	$ \Delta R  < 10\%$	MIL-STD-202 Method 108
Humidity (Steady State)	$T=40^\circ\text{C} \pm 2^\circ\text{C}$ , RH =90%~95%, 1000 hours	$ \Delta R  < 10\%$	MIL-STD-202 Method 103
Low Temperature Storage	$T=-55^\circ\text{C} \pm 3^\circ\text{C}$ , 96 hours	$ \Delta R  < 10\%$	IEC60068-2-1
High Temperature Storage	$T=125^\circ\text{C} \pm 2^\circ\text{C}$ , 96 hours	$ \Delta R  < 10\%$	IEC60068-2-2
Salt Spray	5% salt solution, 48 hours	$ \Delta R  < 10\%$	MIL-STD-202 Method 101
Thermal Shock	100 cycles, $-65^\circ\text{C}$ to $+125^\circ\text{C}$ , 30 minutes@each extreme	$ \Delta R  < (10\%R+0.005\Omega)$	IEC 60068-2-14

## Recommended Solder Curve

### 1. Infrared Reflow:

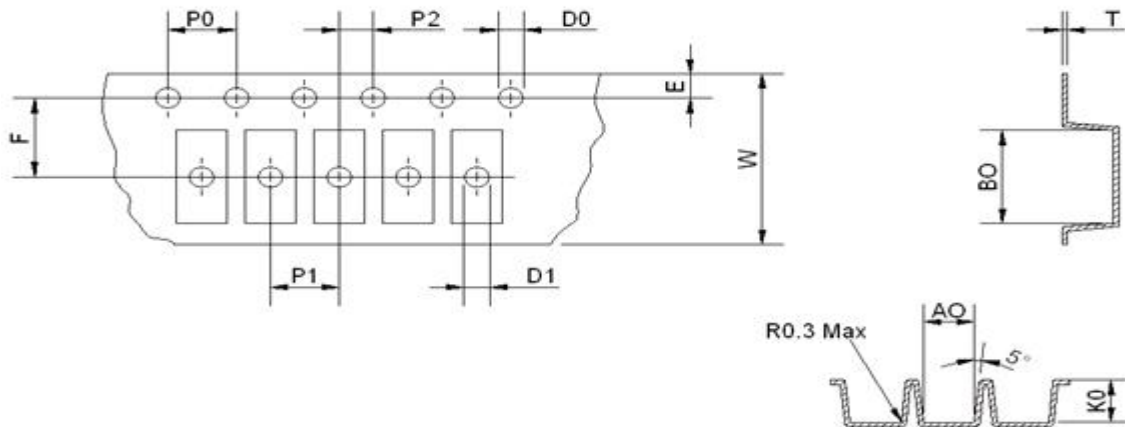
- Temperature: 260°C
- Time: 20sec Max.
- Thickness of solder paste: 0.2mm Max
- Recommend Reflow profile



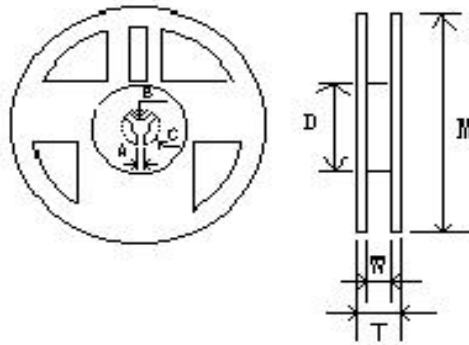
Profile Feature	Pb-Free Assembly
Average Ramp-up Rate( $T_{Smax}$ to $T_p$ )	3°C/sec Max.
Preheat Temperature Min.( $T_{Smin}$ ) Temperature Max.( $T_{Smax}$ ) Time( $T_{Smin}$ to $T_{Smax}$ )	150°C 200°C 60sec~120sec
Peak Temperature( $T_p$ )	260°C
Time within 5°C of actual Peak Temperature( $t_p$ )	20sec
Melting tin time( $t_L$ )	60sec~150sec
Temperature ( $T_L$ )	217°C
Ramp-down Rate	6°C/sec Max.
Time 25°C to peak Temperature	8minutes Max.

## Packaging

- 1000 pieces of fuses in emboss taper and reeled on a 178mm(7 inch) reel.



Type	A0(mm)	B0(mm)	K0(mm)	P0(mm)	P1(mm)	P2(mm)
S6125	2.70±0.10	6.40±0.10	2.70±0.10	4.00±0.10	4.00±0.10	2.00±0.10
Type	E(mm)	F(mm)	D0(mm)	D1(mm)	W(mm)	T(mm)
S6125	1.75±0.10	5.50±0.10	1.50±0.10	1.50±0.25	12.00±0.15	0.25±0.05



Type	M(mm)	W(mm)	T(mm)	A(mm)	B(mm)	C(mm)	D(mm)
S6125	178.00±2.00	12.50±1.00	14.50±1.50	2.00±0.50	13.00±0.50	21.00±0.50	58.00±2.00

## Storage

- The ambient temperature recommended for storage shall be between 5°C~30°C.
- The relative humidity recommended for storage shall be between 25%RH~60%RH.
- Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.